

### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified

| "- TTD MAN   |                  |                   |      |  |  |
|--|------------------|-------------------|------|--|--|
|  | Symbol           | Value             | Unit |  |  |
| Rever <mark>se Voltage</mark>  | V <sub>R</sub>   | 75                | V    |  |  |
| Peak Reverse Voltage   | V <sub>RM</sub>  | 100               | V    |  |  |
| Rectified Current (Average)<br>Half Wave Rectification with Resist. Load<br>at $T_{amb} = 25$ °C and $\ge f \ge 50$ Hz | IO               | 150 <sup>1)</sup> | mA   |  |  |
| Surge Forward Current at t < 1 s and $T_j = 25 \degree C$  | I <sub>FSM</sub> | 500               | mA   |  |  |
| Power Dissipation at T <sub>amb</sub> = 25 °C  | P <sub>tot</sub> | 350 <sup>1)</sup> | mW   |  |  |
| Junction Temperature   | Tj               | 150               | °C   |  |  |
| Stora <mark>ge Temp</mark> erature Range   | Ts               | -65 to +150       | °C   |  |  |
| <sup>1)</sup> Device on fiberglass substrate, see layout   |                  |                   | 1    |  |  |



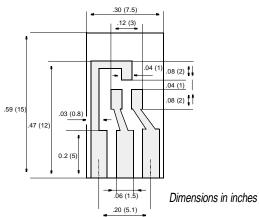


# **IMBD4148**

## **ELECTRICAL CHARACTERISTICS**

Ratings at 25 °C ambient temperature unless otherwise specified

|  | Symbol   | Min. | Тур. | Max.              | Unit           |
|--|--|------|------|-------------------|----------------|
| Forward Voltage<br>at I <sub>F</sub> = 10 mA   | VF   | -    | -    | 1                 | V              |
| Leakage Current<br>at $V_R = 70 V$<br>at $V_R = 70 V$ , $T_j = 150 °C$<br>at $V_R = 25 V$ , $T_j = 150 °C$ | I <sub>R</sub><br>I <sub>R</sub><br>I <sub>R</sub> |      |      | 2.5<br>50<br>30   | μΑ<br>μΑ<br>μΑ |
| Capacitance at $V_F = V_R = 0$   | C <sub>tot</sub>                                   | -    | -    | 4                 | pF             |
| Reverse Recovery Time from $I_F$ = 10 mA to $I_R$ = 10 mA $V_R$ = 6 V, $R_L$ = 100 $\Omega$                | t <sub>rr</sub>                                    | -    | -    | 4                 | ns             |
| Thermal Resistance<br>Junction to Ambient Air  | R <sub>thJA</sub>                                  | -    | -    | 450 <sup>1)</sup> | K/W            |



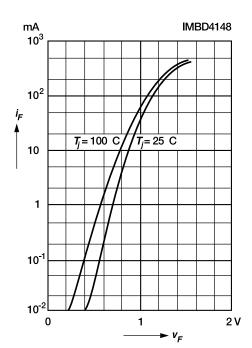
Dimensions in inches (millimeters)

Layout for R<sub>thJA</sub> test Thickness: Fiberglass 0.059 in (1.5 mm) Copper leads 0.012 in (0.3 mm)

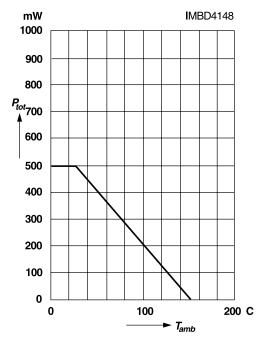
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## **RATINGS AND CHARACTERISTIC CURVES IMBD4148**

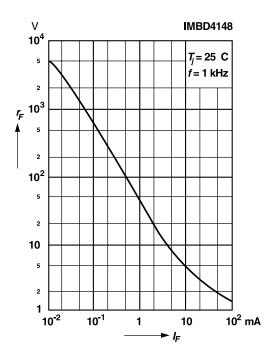
#### **Forward characteristics**



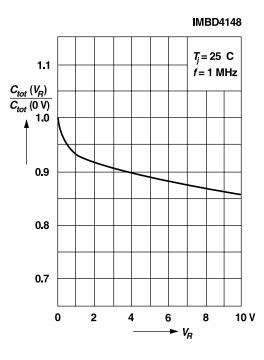




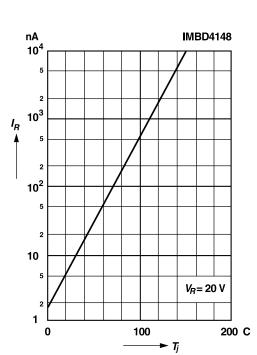
# Dynamic forward resistance versus forward current



Relative capacitance versus reverse voltage

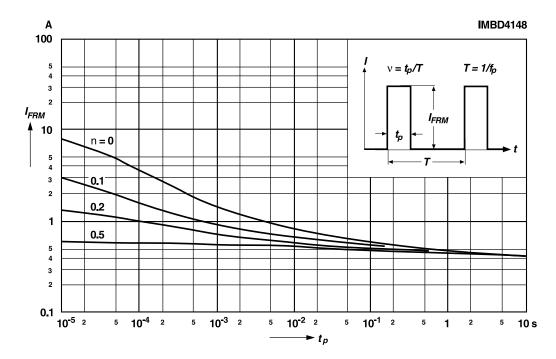


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Leakage current versus junction temperature

Admissible repetitive peak forward current versus pulse duration For conditions, see footnote in table "Absolute Maximum Ratings"



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